


GENERAL TOLERANCE		DWG.NO.	SP169-AN401	PART.NO.	SP169-AN401	DRAWN	L.M.J 2019.12.19	UNIT	mm	SCALE	N O S C A L E
x. ±0.50	x. ±5°	REV.	A	TITLE	Nano SIM With Tray反向沉板0.96	CHECKED		 东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			
. x ±0.25	.x ±2°	SIZE		SHEET	1 0 F 3	APPROVED					
. x x ±0.15	.xx ±1°	A4									

NOTES :

1. MATERIAL :

- 1.1 HOUSING:LCP UL94 S475 V-0, BLACK COLOR.
- 1.2 SHELL:STAINLESS STEEL SUS304.
- 1.3 CONTACT:COPPER ALLOY C5210.

2. FINISH :

- 2.1 CONTACT: GOLD PLATING ON CONTACT AREA, MATTE TIN 80u"MIN ON SOLDER TAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
- 2.2 SHELL: 30U" MIN SOLDERABLE NICKEL PLATED OVER ALL.

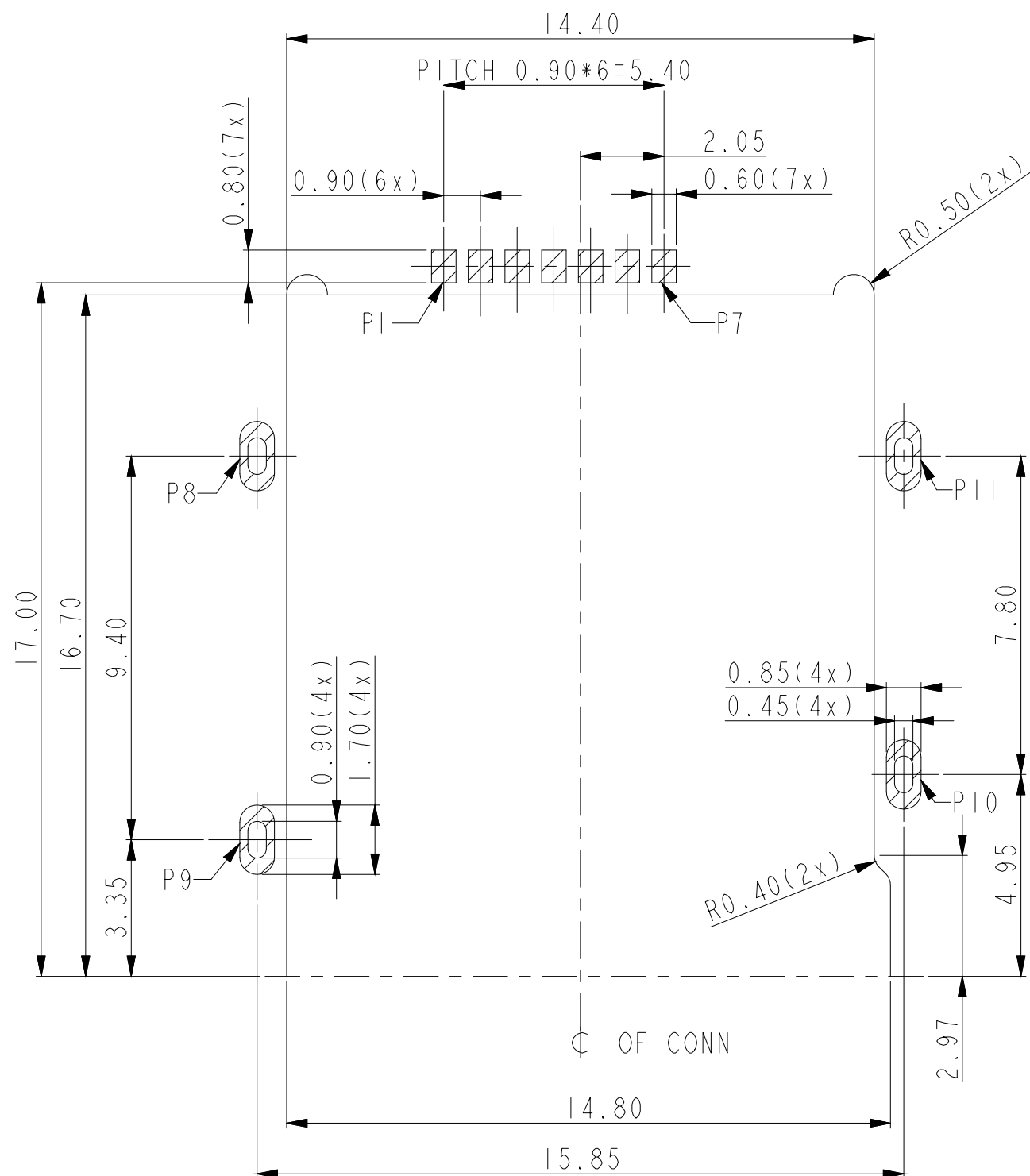
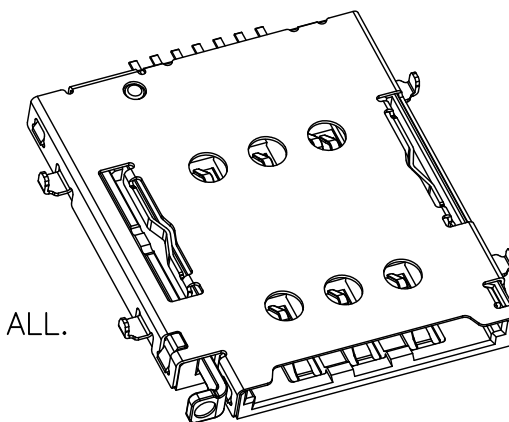
3. ELECTRICAL CHARACTERISTICS:

- 3.1 OPERATING VOLTAGE : 100V AC(rms)/DC.
- 3.2 CURRENT RATING : 0.5 A.
- 3.3 OPERATING TEMPERATURE: -25°C~+85°C.
- 3.4 CONTACT RESISTANCE: 100 m OHMS MAX.
- 3.5 INSULATION RESISTANCE: 1000M OHMS MIN. AT 250VDC.
- 3.6 DIELECTRIC WITHSTANDING VOLTAGE:500 VAC/1MINUTE.

PART.NO.:

SP169-AN401-**

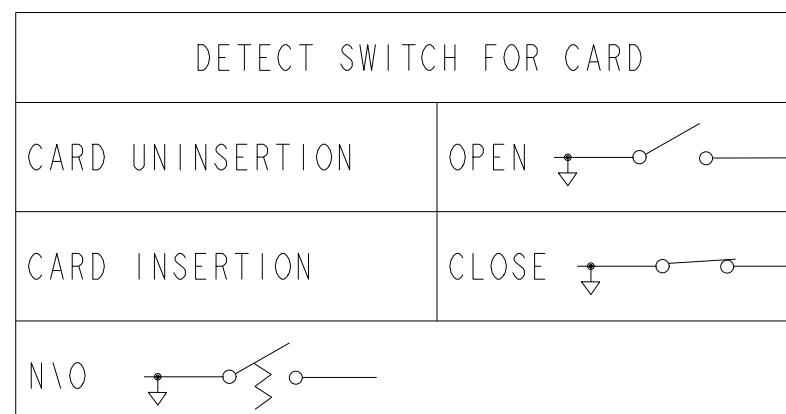
- 42: 功能区镀金1U",锡脚镀雾纯锡至少80U"
- 43: 功能区镀金3U",锡脚镀雾纯锡至少80U"
- 44: 功能区镀金5U",锡脚镀雾纯锡至少80U"
- 45: 功能区镀金10U",锡脚镀雾纯锡至少80U"
- 46: 功能区镀金15U",锡脚镀雾纯锡至少80U"
- 47: 功能区镀金30U",锡脚镀雾纯锡至少80U"



RECOMMENDED P.C.BOARD LAYOUT (TOP VIEW)
TOLERANCES UNLESS OTHERWISE SPEC.±0.05

: PAD AREA

OPEN/CLOSE OF SWITCH :



CONTACT PIN ASSIGNMENT

PIN No.	No. FOR CARD	FUNCTION
P1	C5	GND
P2	CD	CARD DETECT
P3	C6	Vpp
P4	C1	Vcc
P5	C2	RST
P6	C7	I/O
P7	C3	CLK
P8	GND	GND
P9	GND	GND
P10	GND	GND
P11	GND	GND

GENERAL TOLERANCE	DWG.NO.	S P 1 6 9 - A N 4 0 1	PART.NO.	S P 1 6 9 - A N 4 0 1	DRAWN	L . M . J 2 0 1 9 . 1 2	UNIT	mm	SCALE	N O S C A L E
x . ± 0 . 5 0	x . ° ± 5 °	REV.	A	TITLE	Nano SIM With Tray反向沉板0.96	CHECKED				
. x ± 0 . 2 5	. x ° ± 2 °	SIZE	A4	SHEET	2 0 F 3	APPROVED				
. x x ± 0 . 1 5	. x x ° ± 1 °									

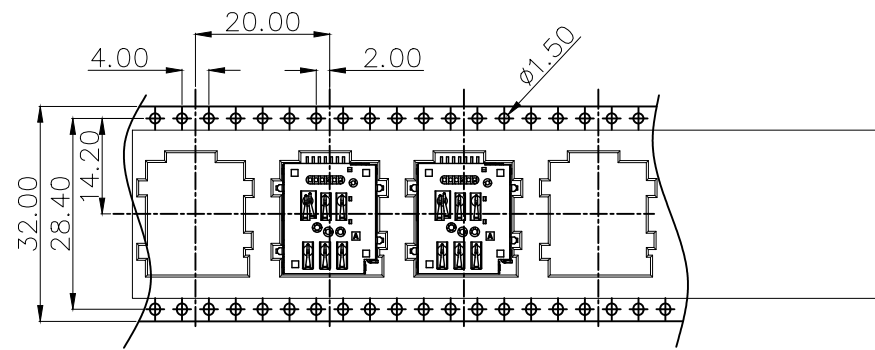
东莞市欧联电子科技有限公司

包装作业规范

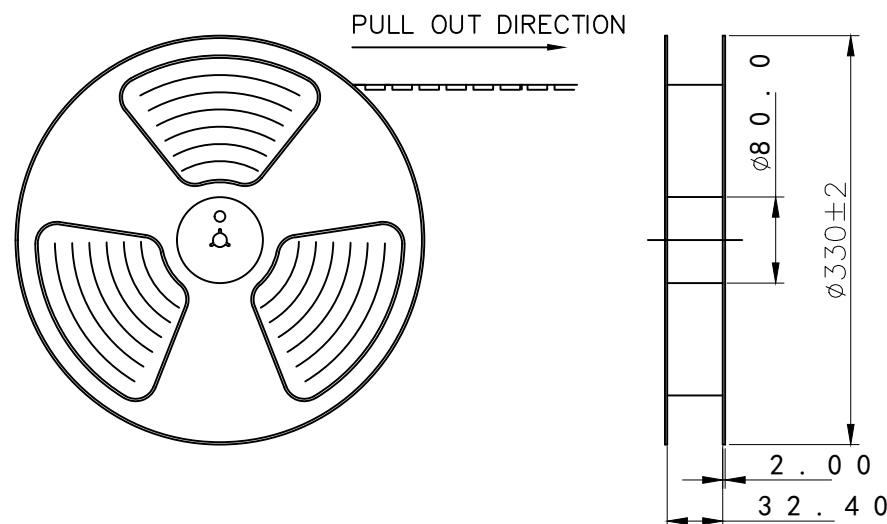
REV.	ECN.NO.	MODIFY.CONTENT
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包装作业图示及说明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

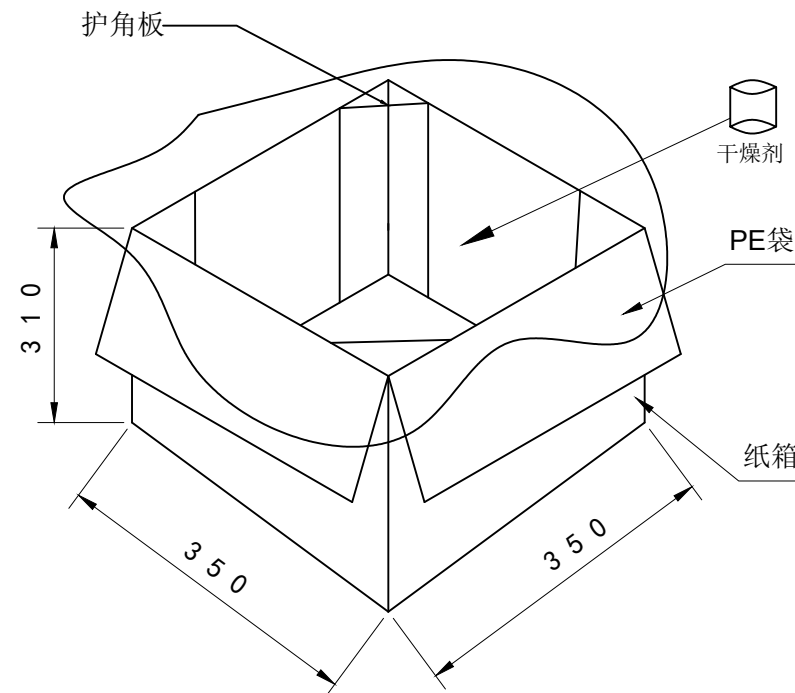
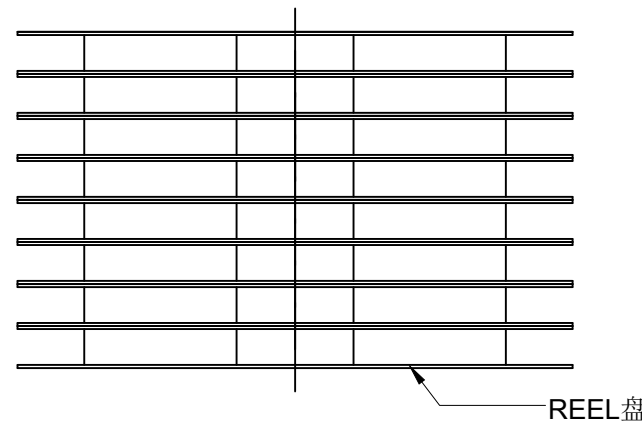
- 一.
- 1) 将成品一一放入REEL包装盘内,依同一方向放入.
 - 2) 包装时,如图所示.
 - 3) 一个REEL包装盘放置1000个成品.



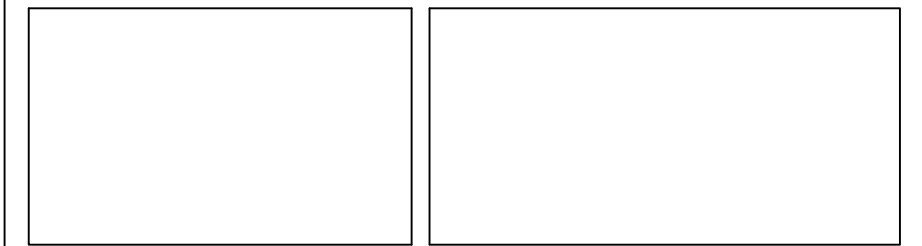
- 二.
- 1) 装盘前先把前面空15pcs产品,然后再开始装盘,尾端也需空15pcs产品,上带加长200mm.
 - 2) 装满成品的REEL包装盘如下图所示.



- 三.
- 1) 每箱装 8 盘REEL包装盘.
 - 2) 每箱放置8000 PCS 的成品.



- 四.
- 1) 用TAPE將紙箱封實.



備註 (REMARK)

1. 若有未裝滿之零數箱,必須以緩衝材塞滿.

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x . ± 0 . 5 0	x . ± 5 °	REV.	A	TITLE	Nano SIM With Tray反向沉板0.96	CHECKED				
. x ± 0 . 2 5	. x ± 2 °	SIZE		SHEET	3 0 F 3	APPROVED				
. x x ± 0 . 1 5	. x x ± 1 °	A4								

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